

ADHESIVE FILM FOR WAFER BACK GRINDING**ABSTRACT**

Disclosed is an adhesive film used to protect a surface of a wafer in a process for grinding a back face of the wafer. More specifically, the present invention relates to an adhesive film for grinding a back face of a wafer in which the adhesive film has uniform adhesion, excellent fillability on a curved portion, and excellent wafer surface protection effect (shock-absorbing effect) in a process for grinding the back face of the wafer on which bumps have been formed, and the adhesive film reduces or suppresses occurrence of adhesive residue when removing (peeling) the adhesive film after grinding the back face, thereby exhibiting excellent workability.

[Fig. 1]